

ABSTRACT OF THE DISCLOSURE

A function module with a built-in heat dissipation fin. The function module includes a first circuit board, a second circuit board, and a heat dissipation fin. The
5 first circuit board includes a first surface with a first ground layer formed thereon. The second circuit board is coupled to the first circuit board, and includes a second surface facing the first surface. A second ground layer is formed on the second surface. The heat dissipation
10 fin is disposed between the first circuit board and the second circuit board, and abuts the first ground layer and the second ground layer respectively.